

TRANSMITTAL

Electronic Version v1.1

Stylesheet Version v1.1.0

Title of Invention	NON-DESTRUCTIVE EVALUATION OF MICROSTRUCTURE AND INTERFACE ROUGHNESS OF ELECTRICALLY CONDUCTING LINES IN SEMICONDUCTOR INTEGRATED CIRCUITS IN DEEP SUB-MICRON REGIME							
Application Number : Date : First Named Applicant: Fen Chen Confirmation Number: Attorney Docket Number: BUR920040182US1								
<p>I hereby certify that the use of this system is for OFFICIAL correspondence between patent applicants or their representatives and the USPTO. Fraudulent or other use besides the filing of official correspondence by authorized parties is strictly prohibited, and subject to a fine and/or imprisonment under applicable law.</p> <p>I, the undersigned, certify that I have viewed a display of document(s) being electronically submitted to the United States Patent and Trademark Office, using either the USPTO provided style sheet or software, and that this is the document(s) I intend for initiation or further prosecution of a patent application noted in the submission. This document(s) will become part of the official electronic record at the USPTO.</p>								
<table border="1"><tr><td>Submitted By:</td><td>Elec. Sign.</td><td>Sign. Capacity</td></tr><tr><td>Anthony J. Canale Registered Number: 51526</td><td>/Anthony J. CANALE, Reg 51526/</td><td>Agent</td></tr></table>			Submitted By:	Elec. Sign.	Sign. Capacity	Anthony J. Canale Registered Number: 51526	/Anthony J. CANALE, Reg 51526/	Agent
Submitted By:	Elec. Sign.	Sign. Capacity						
Anthony J. Canale Registered Number: 51526	/Anthony J. CANALE, Reg 51526/	Agent						

Documents being submitted:	Files
us-fee-sheet	BUR920040182US1-usfees.xml us-fee-sheet.xsl us-fee-sheet.dtd
us-ids	BUR920040182US1-usidst.xml us-ids.dtd us-ids.xsl
us-assignment	BUR920040182US1-usassn.xml us-assignment.xsl us-assignment.dtd BUR920040182Assign1.tif BUR920040182Assign2.tif
us-request	BUR920040182US1-usrequ.xml us-request.dtd us-request.xsl
application-body	BUR920040182ABX.xml application-body.dtd Image1.tif Image2.tif Image3.tif Image4.tif isoamsa.ent isoamsb.ent isoamsc.ent isoamsn.ent isoamso.ent isoamsr.ent isobox.ent isocyr1.ent isocyr2.ent isodia.ent isogr1.ent isogr2.ent isogr3.ent isogr4.ent isolat1.ent isolat2.ent isomfrk.ent isomopf.ent isomscr.ent isonum.ent isopub.ent isotech.ent mathml2.dtd mathml2-qname-1.mod mmlalias.ent mmlextra.ent soextblx.dtd us-application-body.xsl wipo.ent

application-body-pdf-wrap	BUR920040182ABX-pdf-wrap.xml
abstract-pdf	BUR920040182ABX-abst.pdf
claims-pdf	BUR920040182ABX-clms.pdf
description-pdf	BUR920040182ABX-desc.pdf
drawings-pdf	BUR920040182ABX-draw.pdf
us-declaration	BUR920040182dec1.tif
us-declaration	BUR920040182dec2.tif
Comments	
Assignee Address: International Business Machines Corporation, Armonk, NY 10504	